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ELECTRONICS

MacDermid Alpha Electronics Solutions to Highlight the Kester Integration at IPC APEX EXPO 2020 – Product Focus on Affinity ENIG and HiTech Adhesives/Encapsulants

(Waterbury, CT USA) – January 21, 2020 – MacDermid Alpha Electronics Solutions, leaders in innovative electronic interconnect technologies, will feature [Affinity 2.0](#), their highly stable, low corrosion ENIG process and the [ALPHA® HiTech™](#) portfolio of low temperature adhesives, encapsulants, and underfills, at the IPC APEX Conference and Expo, February 1-6, in San Diego, California.

Advanced technologies often bring increased complexity, but well-designed technologies bring performance and simplicity. The [Affinity 2.0](#) process' highly stable activation and nickel plating allows for an ultra-uniform gold deposition with exceptional control. The Circuitry Solutions division will also highlight their complete line of leading-edge copper filled microvia and electroless copper processes.

A recent addition to the Assembly Solutions division, the [ALPHA HiTech series](#) of low temperature adhesives, encapsulants, and underfills is a one-stop bonding platform designed to reduce the scale-up risk for component assemblies deployed into demanding applications. ALPHA HiTech materials exhibit superior drop-shock, impact bend and thermal cycle performance. Their wide processing range has proved to be beneficial for assemblies, especially those incorporating temperature sensitive components. The ALPHA HiTech suite of products has broad application potential for Automotive, Medical, Smartphone, and White Goods assemblies.

This year, MacDermid Alpha Electronics Solutions is proud to welcome Kester to its electronics business. The acquisition of Kester reflects the strategic goals of MacDermid Alpha to expand its expertise and offerings throughout the electronics manufacturing supply chain. "The addition of Kester's talent and expertise will be an important asset in achieving our goal of providing customers with leading products and solutions to ensure highest reliability and performance," said Tim Williams, Vice President of the MacDermid Alpha Assembly Solutions division.

The Kester team will showcase their innovative assembly products, including 268 Flux-Cored Wire, high reliability products: NP505-HR Solder Paste, 275 Flux-Cored Wire, Select-10 Selective Soldering Flux, NF372-TB Soldering Flux and RF550, and solder pastes: NP560, WP616, NP545 and NP505-LT.

For additional information about [MacDermid Alpha's latest technologies and products](#), please visit Booth #1824 at IPC APEX, or contact us @ info@macdermidalpha.com

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